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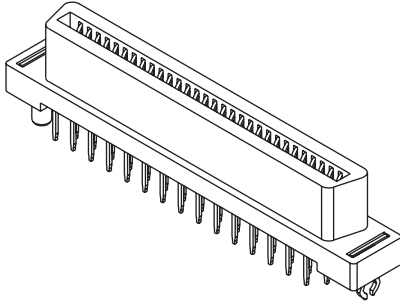
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Jameco Part Number 1976662

1.27mm (.050") Pitch EBBI™ 50D Receptacle

71660
Vertical



Features and Benefits

- Polarized D-shaped leaf-contact connector
- Chamfered lead-in on tails for PCB mounting
- Metal retention clips for mechanical hold down before and after processing
- Low profile—12.50mm (.492") stack height for parallel board packaging
- Mates to standard 1.60mm (.062") PCB card edge with low insertion force
- Surface Mount Compatible

Reference Information

Product Specification: PS-71660
Packaging: Tray
UL File No.: E29179
CSA File No.: LR19980-239A
Mates With: 71661
Designed In: Inches

Electrical

Voltage: 30V
Current: 1.0A
Contact Resistance: 20 milliohms max.
Dielectric Withstanding Voltage: 500V AC
Insulation Resistance: 100 Megohms min.

Mechanical

Contact Retention to Housing: 500g min.
Mating Force: 90g max.
Unmating Force: 15g min.
Normal Force: 90g
Durability: 500 cycles min.

Physical

Housing: High-temperature thermoplastic, UL 94V-0
Retention Clip: Copper Alloy
Contact: Copper Alloy
Plating: 30µ" min. Gold over Nickel in contact area,
100µ" min. Tin over Nickel on tails
Operating Temperature: -40 to +105°C

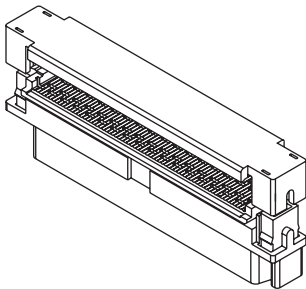
Circuits	Order No.			Lead-free
	PC Tail Length 2.79mm (.110")	PC Tail Length 3.40mm (.134")	PC Tail Length 3.94mm (.155")	
30	15-92-1430	15-92-1030	71660-1630	Yes
40	15-92-1440	15-92-1040	71660-1640	
50	15-92-1450	15-92-1050	71660-1650	
50*		15-92-1550		
60	15-92-1460	15-92-1060	71660-1660	

* Circuit numbers 2-4, 8-11, 14, 17, 20, 23, 26-29, 31-32, 34, 36, 39, 42, 45, 48-49 are advanced terminals for first-mate/last-break mating

Circuits	Order No.			Lead-free
	PC Tail Length 2.79mm (.110")	PC Tail Length 3.40mm (.134")	PC Tail Length 3.94mm (.155")	
68	15-92-1468	15-92-1068	71660-1668	Yes
80	15-92-1480	15-92-1080	71660-1680	
100	15-92-1500	15-92-1100	71660-1700	
120	15-92-1520	15-92-1120	71660-1720	
130	15-92-1530	15-92-1130	71660-1730	

1.27mm (.050") Pitch EBBI™ 50D Receptacle

71660
Vertical
IDT



Features and Benefits

- Polarized D-shaped leaf-contact connector for wire-to-board packaging
- Terminates to 30 AWG solid or stranded .025" ribbon cable or laminated discrete wire cable (including high-performance FEP cable)
- Card slot accommodates standard .062" PCB
- Polarizing key orients connector to PCB

Reference Information

Product Specification: PS-71662
Packaging: Tray (subassembly) and bag (cover)
Tooling Information: Ribbon cable manual press and tool kit
UL File No.: E29179
CSA File No.: LR19980-239A
Mates With: 71661
Designed In: Inches

Electrical

Voltage: 30V
Current: 1.0A
Contact Resistance: 20 milliohms max.
Dielectric Withstanding Voltage: 500V AC
Insulation Resistance: 100 Megohms min.

Mechanical

Contact Retention to Housing: 500g min.
Mating Force: 90g max.
Unmating Force: 15g min.
Normal Force: 90g
Durability: 500 cycles min.

Physical

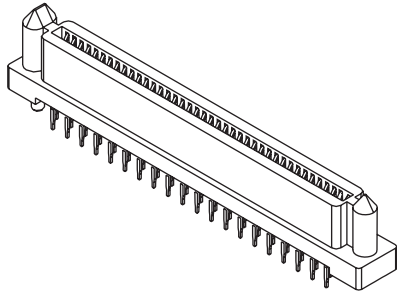
Housing: Thermoplastic, UL 94V-0
Contact: Copper Alloy
Plating: 30µ" min. Gold over Nickel in contact area,
100µ" min. Tin over Nickel on tails
Operating Temperature: -40 to +105°C
Wire Range: 30 AWG solid or stranded Tinned Copper

Circuits	Order No.	Lead-free
30	71660-3530	Yes
40	71660-3540	
50	71660-3550	
60	71660-3560	
68	71660-3568	
80	71660-3580	

1.27mm (.050") Pitch EBBI™ 50D Receptacle

71660

Vertical, Blind Mate



Features and Benefits

- Polarized guide posts on ends provide generous 2.0mm radial lead-in for blind mating
- Chamfered lead-in on tails for PCB mounting
- Press-fit retention pegs for mechanical hold down before and after processing
- Mates to standard 1.60mm (.062") PCB card edge
- First-mate/last-break terminal option available
- Surface Mount Compatible

Reference Information

Product Specification: PS-71660
 Packaging: Tray
 UL File No.: E29179
 CSA File No.: LR19980-239A
 Mates With: 71661-7XXX and 71661-25XX
 Designed In: Inches

Electrical

Voltage: 30V
 Current: 1.0A
 Contact Resistance: 20 milliohms max.
 Dielectric Withstanding Voltage: 500V AC
 Insulation Resistance: 100 Megohms min.

Mechanical

Contact Retention to Housing: 500g min.
 Mating Force: 90g max.
 Unmating Force: 15g min.
 Normal Force: 90g
 Durability: 500 cycles min.

Physical

Housing: High-temperature thermoplastic, UL 94V-0
 Contact: Copper Alloy
 Plating: 30μ" min. Gold over Nickel in contact area,
 100μ" min. Tin over Nickel on tails
 Operating Temperature: -40 to +105°C

Circuits	Order No.			Lead-free
	PC Tail Length 2.79mm (.110")	PC Tail Length 3.40mm (.134")	PC Tail Length 3.94mm (.155")	
30	71660-7030	71660-7230	71660-7630	Yes
40*	71660-7040	71660-7240	71660-7640	
50*	71660-7050	71660-7250	71660-7650	
60	71660-7060	71660-7260	71660-7660	
68*	71660-7068	71660-7268	71660-7668	

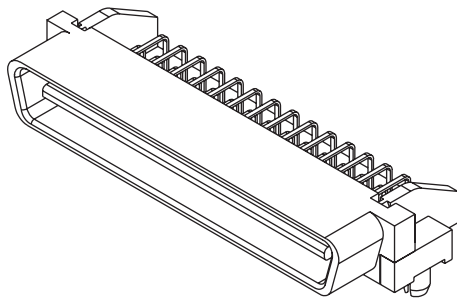
Circuits	Order No.			Lead-free
	PC Tail Length 2.79mm (.110")	PC Tail Length 3.40mm (.134")	PC Tail Length 3.94mm (.155")	
80*	71660-7080	71660-7280	71660-7680	Yes
100	71660-7100	71660-7300	71660-7700	
120	71660-7120	71660-7320	71660-7720	
130	71660-7130	71660-7330	71660-7730	

* Contact Molex for part numbers with advanced terminals for first-mate/last-break mating

1.27mm (.050") Pitch EBBI™ 50D Plug

71661

Right Angle



Features and Benefits

- Polarized D-shaped leaf-contact connector for perpendicular board packaging
- Chamfered lead-in on tails for PCB mounting
- Press-fit retention pegs for mechanical hold down before and after processing
- Surface Mount Compatible

Reference Information

Product Specification: PS-71660
 Packaging: Tray
 UL File No.: E29179
 CSA File No.: LR19980-239A
 Mates With: 71660 and 87552
 Designed In: Inches

Electrical

Voltage: 30V
 Current: 1.0A
 Contact Resistance: 20 milliohms max.
 Dielectric Withstanding Voltage: 500V AC
 Insulation Resistance: 100 Megohms min.

Mechanical

Contact Retention to Housing: 500g min.
 Mating Force: 90g max.
 Unmating Force: 15g min.
 Normal Force: 90g
 Durability: 500 cycles min.

Physical

Housing: High-temperature thermoplastic, UL 94V-0
 Contact: Copper Alloy
 Plating: 30μ" min. Gold over Nickel in contact area,
 100μ" min. Tin over Nickel on tails
 Operating Temperature: -40 to +105°C

Circuits	Order No.		Lead-free
	PC Tail Length 2.79mm (.110")	PC Tail Length 3.18mm (.125")	
30	71661-2030	71661-2330	Yes
40	71661-2040	71661-2340	
50	71661-2050	71661-2350	
60	71661-2060	71661-2360	
68	71661-2068	71661-2368	

Circuits	Order No.		Lead-free
	PC Tail Length 2.79mm (.110")	PC Tail Length 3.18mm (.125")	
80	71661-2080	71661-2380	Yes
100	71661-2100	71661-2400	
120	71661-2120	71661-2420	
130	71661-2130	71661-2430	



PRODUCT SPECIFICATION



LANGUAGE
JAPANESE
ENGLISH

【 1. 適用範囲 SCOPE 】

本仕様書は、_____ 殿 に納入する。

_____ 1. 27 mm ピッチ 基板対基板用 コネクタ _____ について規定する。

This specification covers the 1.27 mm PITCH BOARD TO BOARD CONNECTOR series.

【 2. 製品名称及び型番 PRODUCT NAME AND PART NUMBER 】

製品名称 Product Name		製品型番 Part Number
リセプタクル アセンブリ Receptacle Assembly	無鉛 LEAD FREE	71660-7068
プラグ アセンブリ Plug Assembly	無鉛 LEAD FREE	55087-6819

* : 図面参照 Refer to the drawing.

【 3. 定格 RATINGS 】

項目 Item	規格 Standard	
最大許容電圧 Rated Voltage (MAX.)	30 V	[AC (実効値 rms) / DC]
最大許容電流 Rated Current (MAX.)	1.0 A	
使用温度範囲 Ambient Temperature Range	-40 °C ~ +105 °C *1	

*1 : 通電による温度上昇分も含む。

Including terminal temperature rise.

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SHEET	1-10																		
REVISE ON PC ONLY					TITLE:														
A	新規作成 RELEASED J2004-4675 '04/06/11 J.SASAMORI				1.27mm PITCH BOARD TO BOARD CONN. -LEAD FREE- 製品仕様書														
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J	DESIGN CONTROL				J.SASAMORI	K.TOJO	M.SASAO	2004/06/11											
DOCUMENT NUMBER										FILE NAME	SHEET								
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LANGUAGE

JAPANESE
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【 4. 性能 PERFORMANCE 】

4-1. 電気的性能 Electrical Performance

項目 Item	条件 Test Condition	規格 Requirement
4-1-1 接触抵抗 (初期値) Contact Resistance (Initial)	コネクタを嵌合させ、開放電圧 20mV 以下、短絡電流 10mA にて測定する。 (JIS C5402 5.4) Mate connectors, measure by dry circuit, 20mV MAX. , 10mA. (JIS C5402 5.4)	20 milliohm MAX.
4-1-2 絶縁抵抗 (初期値) Insulation Resistance (Initial)	コネクタを嵌合させ、隣接するターミナル間及びターミナル、アース間に、DC 500V を印加し測定する。 (JIS C5402 5.2/MIL-STD-202 試験法 302) Mate connectors, apply 500V DC between adjacent terminal or ground. (JIS C5402 5.2/MIL-STD-202 Method 302)	100 Megohm MIN.
4-1-3 耐電圧 Dielectric Strength	コネクタを嵌合させ、隣接するターミナル間及びターミナル、アース間に、AC (rms) 500V (実効値) を 1分間 印加する。 (漏洩電流 1mA 以下) (JIS C5402 5.1/MIL-STD-202 試験法 301) Mate connectors, apply 500V AC (rms) for 1 minute between adjacent terminal or ground. (Current leakage 1mA MAX.) (JIS C5402 5.1/MIL-STD-202 Method 301)	異常なきこと No Breakdown

4-2. 機械的性能 Mechanical Performance

項目 Item	条件 Test Condition	規格 Requirement
4-2-1 挿入力・抜去力 Mating / Un-mating Force	毎分 25±3mm の速さで挿入、抜去を行う。 Mate and un-mate connectors at a speed rate of 25±3mm/minute.	挿入力 Mating Force 0.98 N { 100 gf } / CKT. MAX.
		抜去力 Un-mating Force 0.15 N { 151 gf } / CKT. MIN.
4-2-2 ターミナル保持力 Terminal / Housing Retention Force	ハウジングに装着されたターミナルを毎分 25±3mm の速さで軸方向に押す。 Apply axial compressive force on the terminal assembled in the housing at a rate of 25±3 mm/min.	4.41 N { 450 gf } MIN.

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A

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TITLE:

1.27mm PITCH BOARD TO BOARD CONN.

-LEAD FREE-

製品仕様書

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PRODUCT SPECIFICATION



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4-3. その他 Environmental Performance and Others

項目 Item		条件 Test Condition	規格 Requirement	
4-3-1	繰り返し通電 Current Cycling	コネクタを嵌合させ、45分間 通電、15分間 非通電を 240時間 繰り返し、コネクタの温度上昇分を測定する。 Mate connectors together, carry rated current load for 45 minutes on, 15 minutes off for 240 hours, and measure temperature rise of contact.	温度上昇 Temperature Rise	30 °C MAX.
4-3-2	温度上昇 Temperature Rise	コネクタを嵌合させ、最大許容電流を 96時間 通電し、コネクタの温度上昇分を測定する。 Mate connectors together, carry rated current load for 96 hours, and measure temperature rise of contact.	温度上昇 Temperature Rise	30 °C MAX.
4-3-3	繰り返し挿抜 Repeated Mate / Un-mate	1分間 10回 以下の速さで挿入、抜去を 500回 繰り返す。 When mate/un-mate up to 500 cycles repeatedly at a rate of 10 cycles/min.	外観 Appearance	異常なきこと No Damage
			接触抵抗 Contact Resistance	30 milliohm MAX.
4-3-4	耐振動性 Vibration	DC 1mA 通電状態にて、嵌合軸を含む互いに垂直な 3方向 に掃引割合 10~55~10 Hz/分 全振幅 1.5mm の振動を 各2時間 加える。 (MIL-STD-202 試験法 201) Mate connectors and subject to the following vibration conditions, for a period of 2 hours in each of 3 mutually perpendicular axes, passing DC 1mA during the test. Amplitude : 1.5mm P-P Frequency : 10~55~10 Hz Shall be traversed in 1 minute (MIL-STD-202 Method 201)	外観 Appearance	異常なきこと No Damage
			接触抵抗 Contact Resistance	30 milliohm MAX.
			瞬断 Discontinuity	1.0 microsec. MAX.

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項目 Item		条件 Test Condition	規格 Requirement	
4-3-5	耐衝撃性 Shock	DC 1mA 通電状態にて、嵌合軸を含む互いに垂直な 6方向に 490m/s ² { 50G } の衝撃を各3回加える。 (JIS C0041/MIL-STD-202 試験法 213) Mate connectors and subject to the following shock conditions. 3 time of shocks shall be applied for each 6 directions along 3 mutually perpendicular axes, passing DC 1mA current during the test. (Total of 18 shocks) Test Pulse : Half Sine Peak Value : 490m/s ² { 50G } Duration : 11ms (JIS C0041/MIL-STD-202 Method 213)	外観 Appearance	異常なきこと No Damage
			接触抵抗 Contact Resistance	30 milliohm MAX.
			瞬断 Discontinuity	1.0 microsec. MAX.
4-3-6	耐熱性 Heat Resistance	コネクタを嵌合させ、105±2°C の雰囲気中に 96時間 放置後取り出し、1~2時間 室温に放置する。 (JIS C0021/MIL-STD-202 試験法 108) Mate connectors and expose to 105±2°C for 96 hours. Upon completion of the exposure period, the test specimens shall be conditioned at ambient room conditions for 1 to 2 hours, after which the specified measurements shall be performed. (JIS C0021/MIL-STD-202 Method 108)	外観 Appearance	異常なきこと No Damage
			接触抵抗 Contact Resistance	30 milliohm MAX.
4-3-7	耐寒性 Cold Resistance	コネクタを嵌合させ、-40±3°C の雰囲気中に 96時間 放置後取り出し、1~2時間 室温に放置する。 (JIS C0020) Mate connectors and expose to -40±3°C for 96 hours. Upon completion of the exposure period, the test specimens shall be conditioned at ambient room conditions for 1 to 2 hours, after which the specified measurements shall be performed. (JIS C0020)	外観 Appearance	異常なきこと No Damage
			接触抵抗 Contact Resistance	30 milliohm MAX.

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項目 Item		条件 Test Condition	規格 Requirement	
4-3-8	耐湿性 (定常状態) Humidity (Steady State)	コネクタを嵌合させ、60±2°C、相対湿度 90～95% の雰囲気中に 96時間 放置後取り出し、1～2時間 室温に放置する。 (JIS C0022/MIL-STD-202 試験法 103) Mate connectors and expose to 60±2°C, relative humidity 90 to 95% for 96 hours. Upon completion of the exposure period, the test specimens shall be conditioned at ambient room conditions for 1 to 2 hours, after which the specified measurements shall be performed. (JIS C0022/MIL-STD-202 Method 103)	外観 Appearance	異常なきこと No Damage
			接触抵抗 Contact Resistance	30 milliohm MAX.
			耐電圧 Dielectric Strength	4-1-3項満足のこと Must meet 4-1-3
			絶縁抵抗 Insulation Resistance	100 Megohm MIN.
4-3-9	耐湿性 (温度サイクル) Moisture Resostance	コネクタを嵌合させ、第6項 に示す条件にて 10サイクル 行う。 試験後室温に 240時間 放置する。 (MIL-STD-202 試験法 106) Mate connectors and subject to the conditions specified on par. [6] for 10 cycles. After which the test specimens shall be conditioned at ambient room conditions for 240 hours. (MIL-STD-202 Method 106)	外観 Appearance	異常なきこと No Damage
			接触抵抗 Contact Resistance	30 milliohm MAX.
			耐電圧 Dielectric Strength	4-1-3項満足のこと Must meet 4-1-3
			絶縁抵抗 Insulation Resistance	100 Megohm MIN.
4-3-10	温度サイクル Temperature Cycling	コネクタを嵌合させ、-40 ⁺⁰ ₋₃ °C に 30分、+105 ⁺³ ₋₀ °C に 30分。これを 1サイクル として10サイクル 行う。 但し、温度移行時間は 3分以内 とする。試験後 1～2時間 室温に放置する。 (MIL-STD-202 試験法 107) Mate connectors and subject to the following conditions for 10 cycles. Upon completion of the exposure period, the test specimens shall be conditioned at ambient room conditions for 1 to 2 hours, after which the specified measurements shall be performed. 1 cycles a) -40 ⁺⁰ ₋₃ °C 30 minutes b) +105 ⁺³ ₋₀ °C 30 minutes (Transit time shall be within 5 minutes) (MIL-STD-202 Method 107)	外観 Appearance	異常なきこと No Damage
			接触抵抗 Contact Resistance	30 milliohm MAX.
			絶縁抵抗 Insulation Resistance	100 Megohm MIN.

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項 目 Item		条 件 Test Condition	規 格 Requirement	
4-311	混合ガス Mixture	コネクタを嵌合させ、下記条件の混合ガス中に 10日間 放置する。 但し、ガスの速度は 350mm/sec. とする。 温度：30°C、湿度：70% RH 10ppbH ₂ S + 10ppbCl ₂ + 200ppbNO ₂ (Battle Class II) Mate connectors and expose to the following mixed gas condition for 10 days. Linear flow rate to be 350mm/sec. Temperature：30°C, Humidity：70% RH 10ppbH ₂ S + 10ppbCl ₂ + 200ppbNO ₂ (Battle Class II)	外 観 Appearance	異状なきこと No Damage
			接 触 抵 抗 Contact Resistance	30 milliohm MAX.
4-3-12	半田付け性 (DIP) Solderability	ターミナルをフラックスに浸し、本体取付け基準面より 1.2mm まで、245±5°C の半田に 3±0.5秒 浸す。 After dipping soldertails into the flux, solder as flows ; Solder Time : 3±0.5 sec. Solder Temperature : 245±5°C (Up to 1.2mm from the bottom of the housing)	濡れ性 Solder Wetting	浸漬面積の95%以上 95% of immersed area must show no voids, pin holes.
4-3-13	半田耐熱性 (DIP) Resistance to Soldering Heat	ターミナルをフラックスに浸し、本体取付け基準面より 1.2mm まで、260±5°C の半田に 最大5秒 浸す。 Soldering Time : 5 sec. Max. Solder Temperature : 260±5°C (Up to 1.2mm from the bottom of the housing)	外 観 Appearance	端子ガタ、割れ等 異状なきこと No Damage
4-3-14	半田付け性 (SMT) Solderability	端子先端より 0.5mm の位置まで、245±5°C の半田に 3±0.5秒 浸す。 Dip solder tails into the molten solder (held at 245±5°C) up to 0.5mm from the bottom of the housing for 3±0.5 sec.	濡れ性 Solder Wetting	浸漬面積の95%以上 95% of immersed area must show no voids, pin holes.

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項 目 Item		条 件 Test Condition	規 格 Requirement	
4-3-15	半田耐熱性 (SMT) Resistance to Soldering Heat	(リフロー時) <u>When reflowing</u> 第7項 の条件にて、2回 リフローを行う。 Refer to paragraph 7, two times.	外 観 Appearance	端子ガタ、割れ等 異状なきこと No Damage
		(手半田) <u>Soldering iron method</u> 端子先端より 0.5mm の位置まで、370~ 400°C の半田ゴテにて 最大5秒 加熱する。 但し、異常な加圧のないこと。 Heat soldertail using a soldering iron at 370 ~400°C witein 0.5mm from bottom of the soldertails for 5 seconds MAX. However, without too much pressure to the terminal pin.		

() : 参考規格 Reference Standard
 { } : 参考単位 Reference Unit

【 5. 外観形状、寸法及び材質 PRODUCT SHAPE, DIMENSIONS AND MATERIALS 】

図面参照 Refer to the drawing.

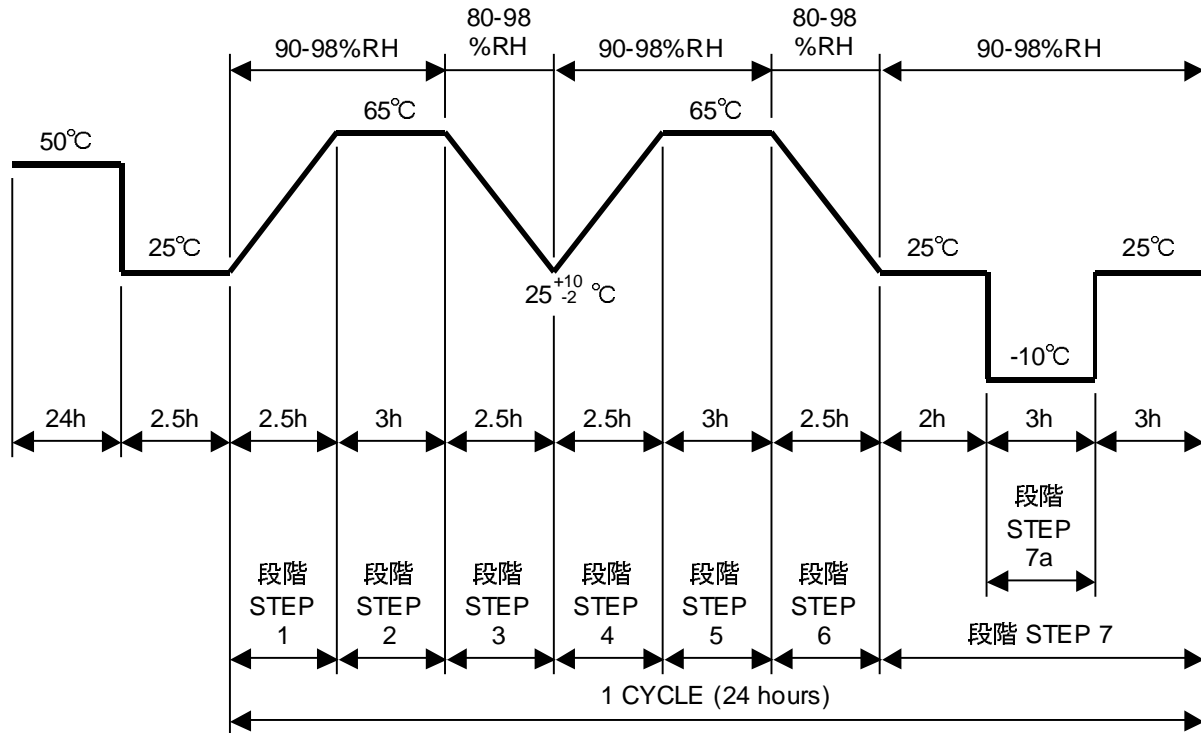
REVISE ON PC ONLY		TITLE:	
A	SEE SHEET 1 OF 10	1.27mm PITCH BOARD TO BOARD CONN. -LEAD FREE- 製品仕様書	
	REV.	DESCRIPTION	THIS DOCUMENT CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INC. AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION
DOCUMENT NUMBER PS-55087-002		FILE NAME PS55087002	SHEET 7 OF 10



【 6. 耐湿性試験条件 MOISTURE RESISTANCE CONDITIONS 】

MIL-STD-202 試験法106

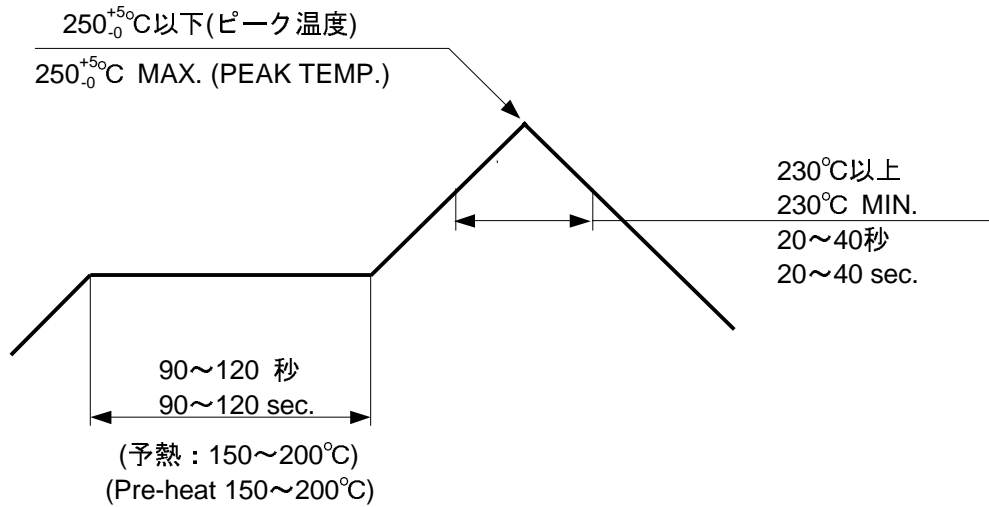
(MIL-STD-202 Method 106)



REVISE ON PC ONLY		TITLE:	
A	SEE SHEET 1 OF 10	1.27mm PITCH BOARD TO BOARD CONN.	
		-LEAD FREE- 製品仕様書	
REV.	DESCRIPTION	THIS DOCUMENT CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INC. AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION	
DOCUMENT NUMBER PS-55087-002		FILE NAME PS55087002	SHEET 8 OF 10



【 7. 赤外線リフロー条件 INFRARED REFLOW CONDITION 】



温度条件グラフ
 (温度は基板パターン面)
TEMPERATURE CONDITION GRAPH
 (TEMPERATURE ON THE SURFACE OF P.C.BOARD PATTERN)

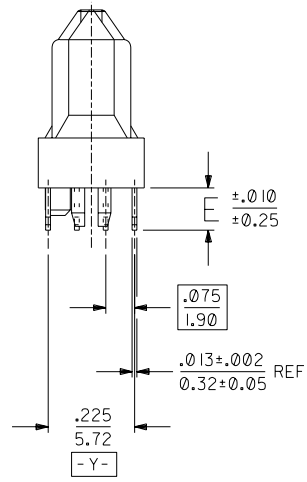
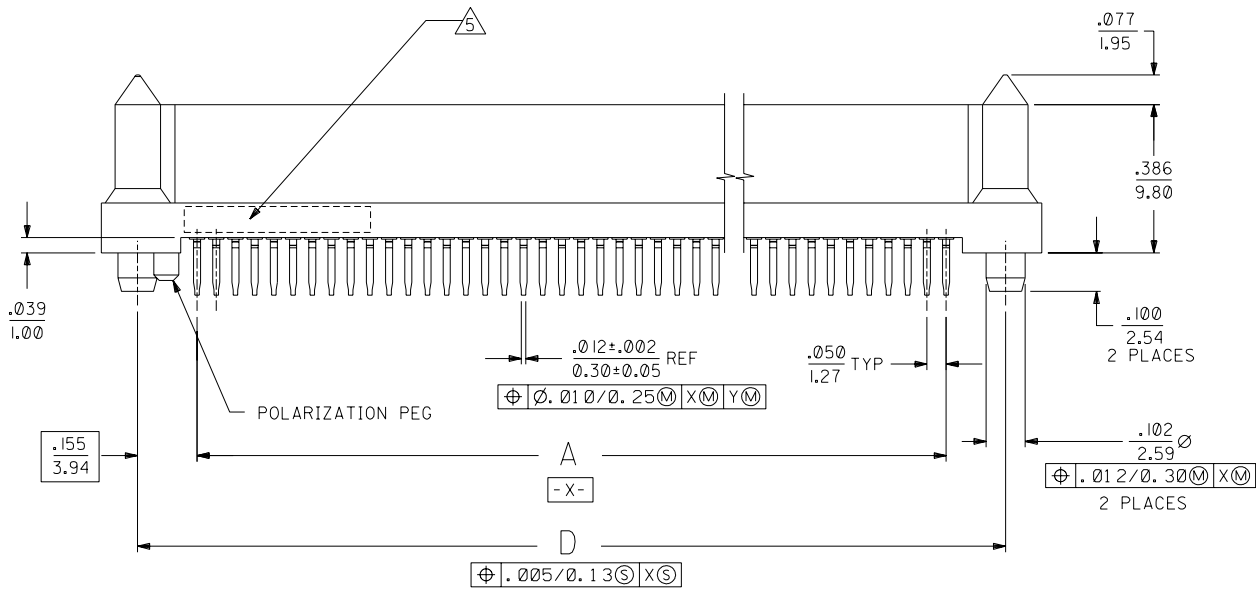
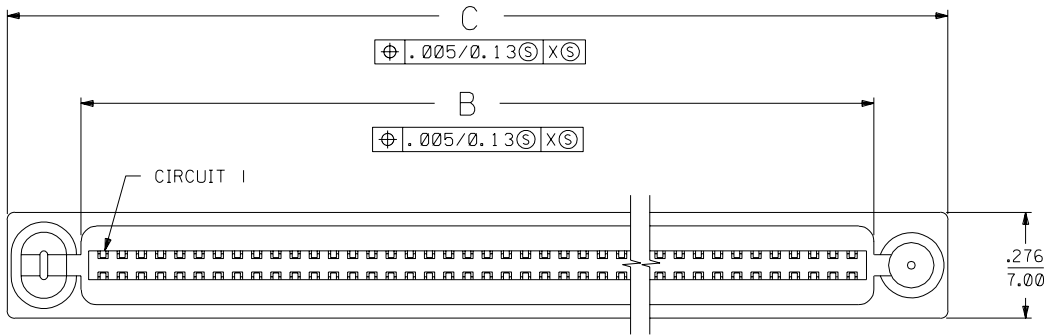
注記 ; 本リフロー条件に関しては、リフロー装置及び基板などにより条件が異なりますので、
 事前にリフロー評価の確認をお願い致します。

NOTE ; Please check the reflow soldering condition by your own devices beforehand.
 Because the condition changes by the soldering devices, P.C.Boards, and so on.

REVISE ON PC ONLY		TITLE:	
A	SEE SHEET 1 OF 10	1.27mm PITCH BOARD TO BOARD CONN.	
	REV.	DESCRIPTION	-LEAD FREE- 製品仕様書
DOCUMENT NUMBER		THIS DOCUMENT CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INC. AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION	
PS-55087-002		FILE NAME	SHEET
		PS55087002	9 OF 10
EN-37-1(019)			

NOTES:

- 1) MATERIALS:
HOUSING- LCP, GLASS FILLED, 94V-0, BLACK.
TERMINALS- COPPER ALLOY
- 2) FINISH:
TERMINALS:
.000030/(0.00076) MINIMUM GOLD IN CONTACT AREA AND
.000050/(0.00127) MINIMUM TIN IN TAIL AREA OVER
.000075/(0.00191) MINIMUM NICKEL UNDERPLATE OVERALL.
- 3) ASSEMBLY MATES WITH MOLEX P/N SDA-71661-7***.
CONFORMS TO PRODUCT SPECIFICATION PS-71660.
- 4) RECOMMENDED P.C. BOARD THICKNESS IS .062/1.6 mm.
- 5) FOUR DIGIT DATE CODE TO BE LOCATED ON SURFACE AS SHOWN.



NOTE FOR LEAD FREE CONVERSION:

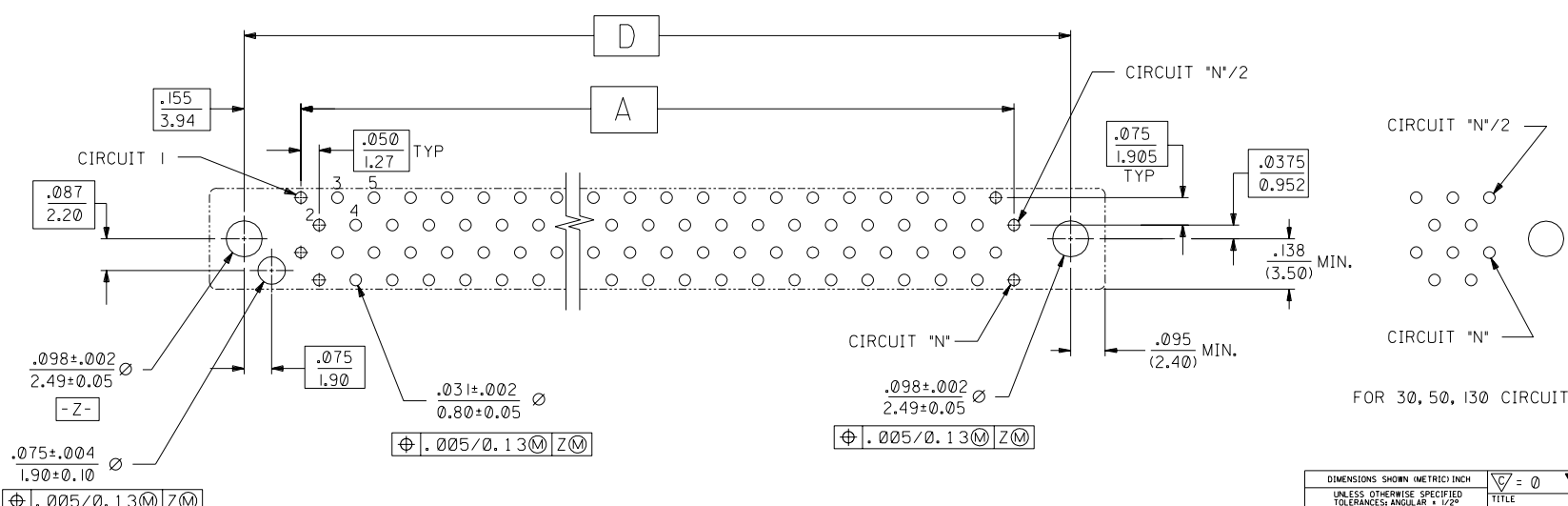
THE PRIMARY SHIPPING CARTON WILL BE LABELED "COMPLIANT TO RoHS DIRECTIVE 2002/95/EC AND ELV ANNEX II OF DIRECTIVE 2000/53/EC". CARTONS WITHOUT THIS LABEL MAY CONTAIN PRODUCT WITH LEAD.

N	ADD LONG TAIL UCP2004-1302 RWWHITE 04/07/14
M	LEAD FREE CONV ECN UCP2004-2096 RKADAMS 04/04/29
L	REVISED PER UDT 2000-1231 ACHAMMER 00/06/07
K	REVISED PER ECN U71314 ACHAMMER 97/4/25
J	REVISED PER ECN U70133 ACHAMMER 96/8/19
I	REVISED PER ECN U70090 ACHAMMER 96/7/26
H	REVISED PER ECN U61278 5-2-96 DCA
G	REVISED PER ECN U60641 11-29-95 DRS
F	REVISED PER ECN U60564 11-8-95 RAN
E	REVISED PER ECN U50229 9-23-94 RAN
D	REVISED PER ECN U50090 8-30-94 RAN
C	REVISED PER ECN U40506 4-15-94 RAN
B	REVISED PER ECN U40305 3-4-94 RAN
A	INITIAL RELEASE PER ECN U31832 12-15-93 RAN

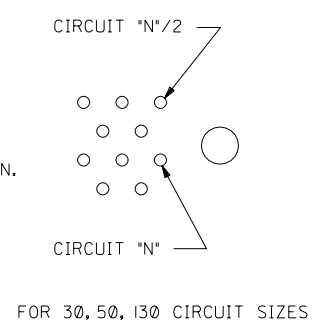
2	N		
1	N		
MFG.	SH.	REV.	LTR.

DIMENSIONS SHOWN (METRIC) INCH UNLESS OTHERWISE SPECIFIED TOLERANCES: ANGULAR ± 1/2°		▽ = 0 ▼ = 0		REVISE ONLY ON CAD SYSTEM	
INCH METRIC		TITLE			
3 PLACE ± .005	---	SALES ASSEMBLY EBBI 50D VERTICAL RCPT BLIND MATE CONNECTOR			
2 PLACE ± --- ± 0.13	---				
1 PLACE --- ± ---	---				
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		MOLEX INCORPORATED		SHEET NO. DATE 1 OF 2 11/17/93	
PART NO.		SEE TABLE		SDA-71660-7***	
DRWG. BY: RAN	CHK'D. BY: RAN	FILE NAME: 571660X7	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INC. AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		DIV. SIZE: C C

ITEM NUMBER	CKT ('N')	A	B	C	D	E
71660-7030	30	.700 (17.78)	.815 (20.70)	1.199 (30.45)	1.010 (25.65)	.110 (2.79)
71660-7040	40	.950 (24.13)	1.065 (27.05)	1.449 (36.80)	1.260 (32.00)	
71660-7050	50	1.200 (30.48)	1.315 (33.40)	1.699 (43.15)	1.510 (38.35)	
71660-7060	60	1.450 (36.83)	1.565 (39.75)	1.949 (49.50)	1.760 (44.70)	
71660-7068	68	1.650 (41.91)	1.765 (44.83)	2.149 (54.58)	1.960 (49.78)	
71660-7080	80	1.950 (49.53)	2.065 (52.45)	2.449 (62.20)	2.260 (57.40)	
71660-7100	100	2.450 (62.23)	2.565 (65.15)	2.949 (74.90)	2.760 (70.10)	
71660-7120	120	2.950 (74.93)	3.065 (77.85)	3.449 (87.60)	3.260 (82.80)	
71660-7130	130	3.200 (81.28)	3.315 (84.20)	3.699 (93.95)	3.510 (89.15)	
71660-7230	30	.700 (17.78)	.815 (20.70)	1.199 (30.45)	1.010 (25.65)	
71660-7240	40	.950 (24.13)	1.065 (27.05)	1.449 (36.80)	1.260 (32.00)	
71660-7250	50	1.200 (30.48)	1.315 (33.40)	1.699 (43.15)	1.510 (38.35)	
71660-7260	60	1.450 (36.83)	1.565 (39.75)	1.949 (49.50)	1.760 (44.70)	
71660-7268	68	1.650 (41.91)	1.765 (44.83)	2.149 (54.58)	1.960 (49.78)	
71660-7280	80	1.950 (49.53)	2.065 (52.45)	2.449 (62.20)	2.260 (57.40)	
71660-7300	100	2.450 (62.23)	2.565 (65.15)	2.949 (74.90)	2.760 (70.10)	
71660-7320	120	2.950 (74.93)	3.065 (77.85)	3.449 (87.60)	3.260 (82.80)	
71660-7330	130	3.200 (81.28)	3.315 (84.20)	3.699 (93.95)	3.510 (89.15)	
71660-7630	30	.700 (17.78)	.815 (20.70)	1.199 (30.45)	1.010 (25.65)	.155 (3.94)
71660-7640	40	.950 (24.13)	1.065 (27.05)	1.449 (36.80)	1.260 (32.00)	
71660-7650	50	1.200 (30.48)	1.315 (33.40)	1.699 (43.15)	1.510 (38.35)	
71660-7660	60	1.450 (36.83)	1.565 (39.75)	1.949 (49.50)	1.760 (44.70)	
71660-7668	68	1.650 (41.91)	1.765 (44.83)	2.149 (54.58)	1.960 (49.78)	
71660-7680	80	1.950 (49.53)	2.065 (52.45)	2.449 (62.20)	2.260 (57.40)	
71660-7700	100	2.450 (62.23)	2.565 (65.15)	2.949 (74.90)	2.760 (70.10)	
71660-7720	120	2.950 (74.93)	3.065 (77.85)	3.449 (87.60)	3.260 (82.80)	
71660-7730	130	3.200 (81.28)	3.315 (84.20)	3.699 (93.95)	3.510 (89.15)	



RECOMMENDED PC BOARD LAYOUT Δ
 COMPONENT SIDE
 FOR 40, 60, 68, 80, 100, 120 CIRCUIT SIZES



DIMENSIONS SHOWN (METRIC) INCH		▽ = 0 ▼ = 0		REVISE ONLY ON CAD SYSTEM	
UNLESS OTHERWISE SPECIFIED TOLERANCES: ANGULAR ± 1/2°					
3 PLACE	± .005	---	---		
2 PLACE	± ---	± 0.13	---		
1 PLACE	---	± ---	---		
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS					
DRWG. BY: RAN		CHK'D. BY: RAN		SCALE: 4: 1	
APP'D. BY: CAB		FILE NAME: 571660BXT		SHEET NO.: 2	
		DATE: 11/17/93		U.S.A.	
PART NO. SDA-71660-7***		DRWG. NO. SDA-71660-7***		REV. LTR.	
SEE TABLE		MFG. SH. REV. LTR. REVISIONS		N SEE SHEET I	
				K SEE SHEET I	

71660